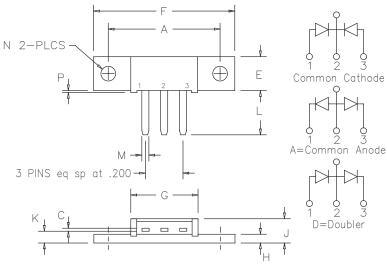
# Schottky MiniMod



Dim	. Inches		Millimeter	
	Minimum	Maximum	Minimum	Maximum Notes
А	1.180	1.195	29.97	30.35
С	.027	.037	0.69	0.94
E	.350	.370	8.89	9.40
F	1.490	1.510	37.85	38.35
G	.695	.715	17.65	18.16
Н	.088	.098	2.24	2.49
J	.240	.260	6.10	6.60
K	.115	.135	2.92	3.43
L	.460	.480	11.68	12.19
М	.065	.085	1.65	2.16
N	.151	.161	3.84	4.09 Dia.
Р	.015	.025	0.38	0.64

Note: Baseplate Common with Pin 2

Microsemi Catalog Number	Industry Part Number	Working Peak Reverse Voltage	Repetitive Peak Reverse Voltage
FST8080* FST8090* FST80100*	83CNQ080, A 83CNQ100, A	80V 90V 100V	80V 90V 100V

\*Add the Suffix A for Common Anode, D for Doubler

- Schottky Barrier Rectifier
- Guard ring protection
- 2X40 Amperes avg.
- 175°C junction temperature
- Reverse energy tested
- VRRM 80 to 100 volts
- ROHS Compliant

### Electrical Characteristics

Average forward current per pkg Average forward current per leg Maximum surge current per leg Max repetitive peak reverse current per leg Max peak forward voltage per leg Max peak forward voltage per leg Max peak reverse current per leg Max peak reverse current per leg Typical junction capacitance per leg

F(AV) 80 Amps F(AV) 40 Amps FSM 800 Amps R(OV) 2 Amps VFM 0.62 Volts VFM 0.82 Volts RM 50 mA I<sub>RM</sub> 2 mA C<sub>J</sub> 1450 pF

 $^{T}C$  = 143°C, square wave,  $^{R}\Theta$ JC = 0.5°C/W  $^{T}C$  = 143°C, square wave,  $^{R}\Theta$ JC = 1.0°C/W 8.3 ms, half sine,  $TJ = 175^{\circ}C$ f = 1 KHZ, 25°C, 1µsec square wave FM = 40A: TJ = 175°C\*
FM = 40A: TJ = 25°C\*
VRRM, TJ = 125°C\*
VRRM, TJ = 25°C
VR = 5.0V, TC = 25°C

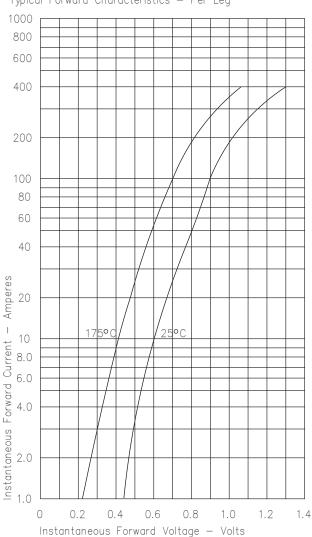
\*Pulse test: Pulse width 300 µsec, Duty cycle 2%

#### Thermal and Mechanical Characteristics -55°C to 175°C -55°C to 175°C TSTG Storage temp range TJ Operating junction temp range Rejc 1.0°C/W Junction to case Max thermal resistance per leg Max thermal resistance per pkg Rejc 0.5°C/W Junction to case Recs 0.3°C/W Typical thermal resistance (greased) Case to sink Mount base torque 10 inch pounds maximum Weight 0.3 ounce (8.4 grams) typical



## FST8080 - FST80100

Figure 1 Typical Forward Characteristics — Per Leg



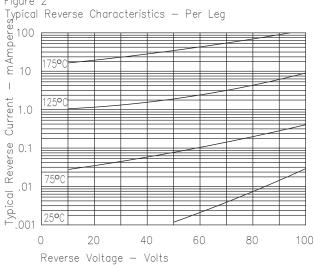


Figure 3 Typical Junction Capacitance — Per Leg

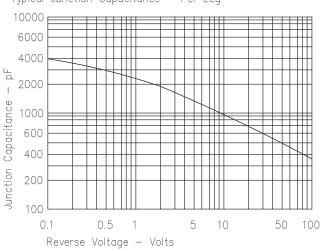
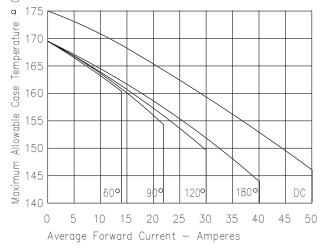
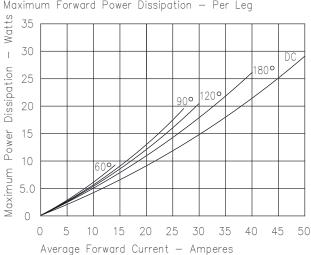


Figure 4 Forward Current Derating - Per Leg



Maximum Forward Power Dissipation - Per Lea





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